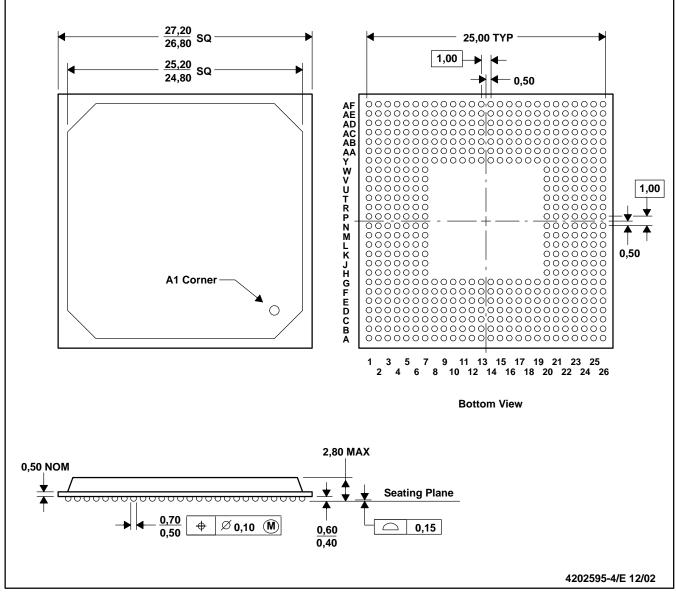
MECHANICAL DATA

MPBG296B - JUNE 2002 - REVISED DECEMBER 2002

GNZ (S-PBGA-N532)

PLASTIC BALL GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Flip chip application only.
 - D. Substrate color may vary.



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